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APR 13 2007

AMENDMENTS TO THE CLAIMS:

Claim 1. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element including a substrate, wherein light radiates from a light emission surface of the substrate of said light emitting element, the light emission surface being provided on the substrate opposite to an electrode forming surface of the substrate; and

a transparent structure mounted on the light emission surface of the substrate, wherein the transparent structure is optically connected with the light emission surface and has a light distribution characteristic based on a three-dimensional shape of the transparent structure; ~~and~~

~~a p-electrode and an n-electrode formed opposite to the light emission surface of the light emitting element~~, wherein the transparent structure comprise a side surface through which to allow the light to be discharged from the transparent structure.

Claim 2. (Canceled).

Claim 3. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a thickness of half that of the semiconductor light emitting element to twice the length of a shorter side of the semiconductor light emitting element.

Claim 4. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a microscopic uneven surface to diffuse light.

Claim 5. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a reflection layer formed on its surface.

Claim 6. (Previously presented) The light emitting apparatus according to claim 17, wherein:

one of the lead frames has a cup portion, and

the transparent structure is fixed on the cup portion through adhesive resin with light

diffusion material mixed therein.

Claim 7. (Previously presented) The light emitting apparatus according to claim 17, wherein:

the electrodes do not transmit light.

Claim 8. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface provided on the substrate of the semiconductor light emitting element opposite an electrode forming surface of the substrate;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is mounted on the light emission surface of the substrate and optically connected with the light emission surface and has a light distribution characteristic based on a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure, the light transmitting resin including a phosphor to wavelength-convert light emitted from the semiconductor light emitting element~~; and~~

~~a p-electrode and an n-electrode formed opposite to the light emission surface of the light emitting element~~, wherein the transparent structure comprises a side surface through which to allow the light to be discharged from the transparent structure.

Claim 9. (Original) The light emitting apparatus according to claim 8, wherein:

the light transmitting resin contains two or more kinds of phosphors.

Claim 10. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises the substrate, a buffer layer, an n-type semiconductor layer, a light-emitting layer, and a p-type semiconductor layer.

Claim 11. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises a gallium nitride system

compound semiconductor.

Claim 12. (Previously Presented) The light emitting apparatus according to claim 1, wherein the transparent structure comprises a light transmitting material comprising at least one of SiO_2, Al_2O_3, SiC, Si_3N_4, AlN, ZrO_2, borosilicate glass, and alumino-silicate glass.

Claim 13. (Previously Presented) The light emitting apparatus according to claim 1, wherein the substrate comprises sapphire.

Claim 14. (Previously presented) The light emitting apparatus according to claim 1, wherein the transparent structure is bonded to the substrate by an adhesive layer.

Claim 15. (Previously Presented) The light emitting apparatus according to claim 14, wherein the adhesive layer comprises a transparent adhesive.

Claim 16. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface provided on the substrate of the semiconductor light emitting element opposite to an electrode forming surface of the substrate;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is mounted on the light emission surface of the substrate and optically connected with the light emission surface and has a light distribution characteristic based on a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure~~; and~~

~~a p-electrode and an n-electrode formed opposite to the light emission surface of the light emitting element~~, wherein the transparent structure comprises a side surface through which to allow the light to be discharged from the transparent structure ~~has a length in the horizontal direction greater than that of the semiconductor light emitting element~~.

Claim 17. (Previously presented) The light emitting apparatus according to claim 1, further comprising lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires.

Claim 18. (Previously presented) The light emitting apparatus according to claim 1, further comprising light transmitting resin that seals the semiconductor light emitting element and the transparent structure.

Claim 19. (Previously presented) The light emitting apparatus according to claim 8, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.

Claim 20. (Previously presented) The light emitting apparatus according to claim 16, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.

Claim 21. (New) The light emitting apparatus according to claim 1, wherein the side surface comprises an inclined plane.

Claim 22. (New) The light emitting apparatus according to claim 8, wherein the side surface comprises an inclined plane.

Claim 23. (New) The light emitting apparatus according to claim 16, wherein the side surface comprises an inclined plane.